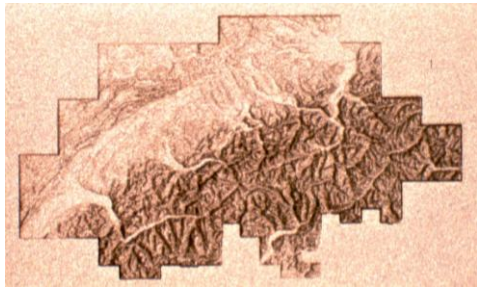


Powerful, flexible, and cost-effective picosecond lasers for industrial micromachining

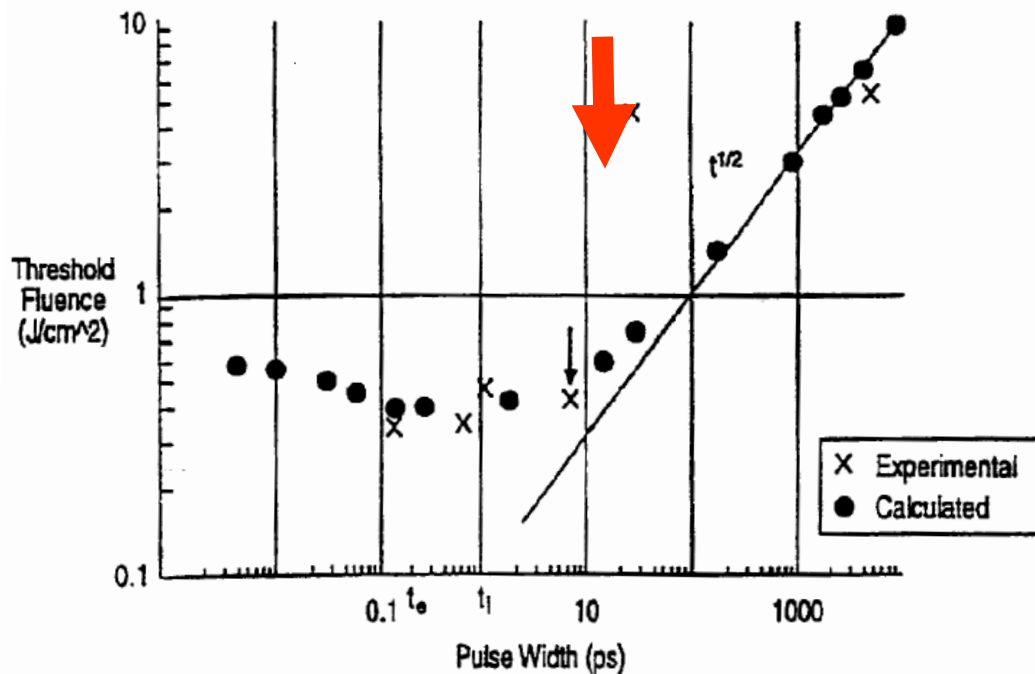


Dr. Kurt Weingarten
kw@time-bandwidth.com

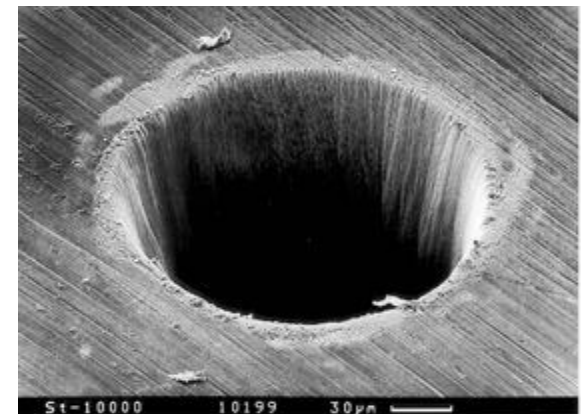
Material processing: "long" versus "short" pulses

Picosecond pulses can cut through "anything" with a very low amount of heating / residual damage

"Cold ablation" starts at around 10 ps pulsewidth



Why? Peak Power required to start ablation is reached at lower pulse energy with shorter pulses



Why picoseconds?

- **Substantial process advantages compared to nanosecond pulses for micromachining**
 - smaller heat-affected zone (less than 1 micron typical)
 - less micro-cracking
 - less recast
 - with substantially faster speed / productivity (depending on process)
 - higher quality ↔ higher speed ↔ (lower cost)
- **Substantial system advantages compared to femtosecond pulses**
 - system much less complex and lower costs
 - dispersion of picosecond pulses not an issue
 - bandwidth of femtosecond pulses can degrade scanner performance
 - system components more proven in industrial environments
 - power scaling currently possible for increased process speeds
 - “Most of the advantages of femtosecond lasers but much simpler / scalable”
 - Femtosecond systems more applicable for “2-photon” processes

DUETTO™ - Integrated Industrial MOPA product family

Master Oscillator Power Amplifier diode-pumped picosecond laser system - architecture

Seed oscillator

- based on Lynx industrial laser with >decade of proven field reliability
- 10 nJ, 10 ps, 1064 nm pulses
- **High-rep pulses seed amplifier stage with user-selectable pulse rate**



Pulse
Picker

Amplifier stage(s)

- based on field-proven 10W Cheetah system
- amplifies to >100 μ J (>40 dB gain)

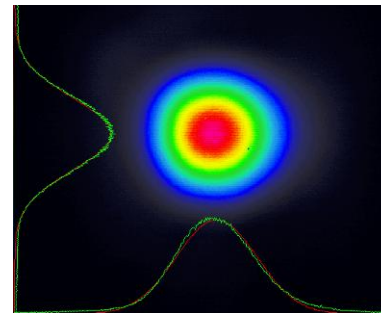
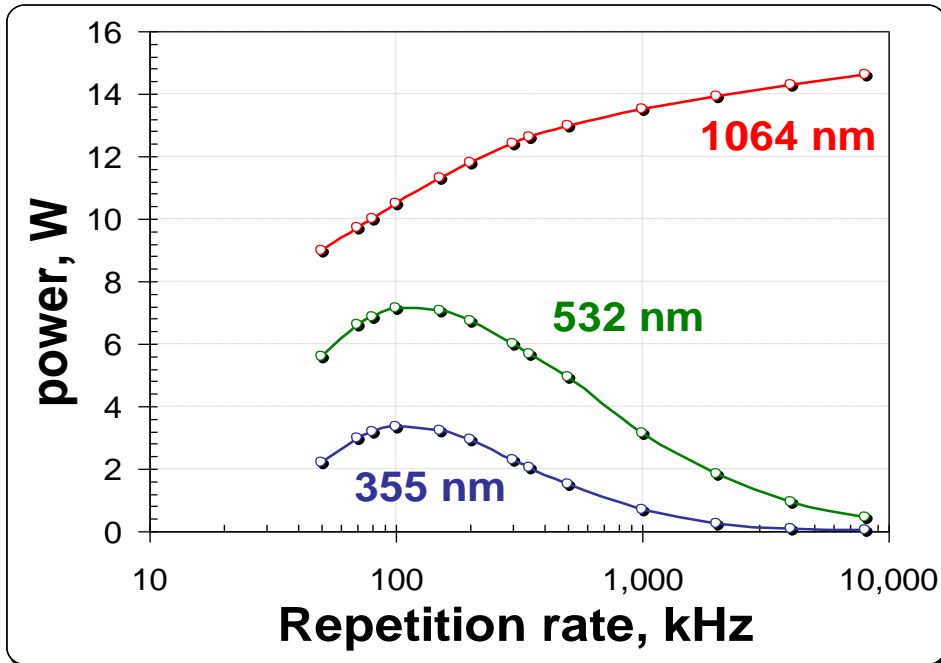


Duetto Integrated MOPA

DUETTO - key performance parameters

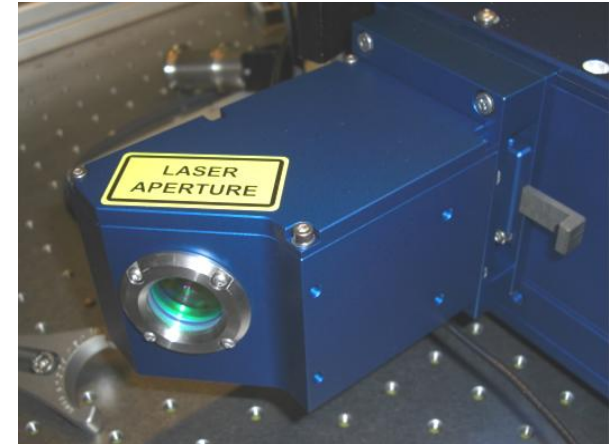


output power	up to 15 W
repetition rate	50 kHz – 8 MHz
pulse energy	up to 200 μ J
pulse width	10 ps
peak power	up to 20 MW
wavelength	1064 nm
M^2 (TEM ₀₀)	< 1.3



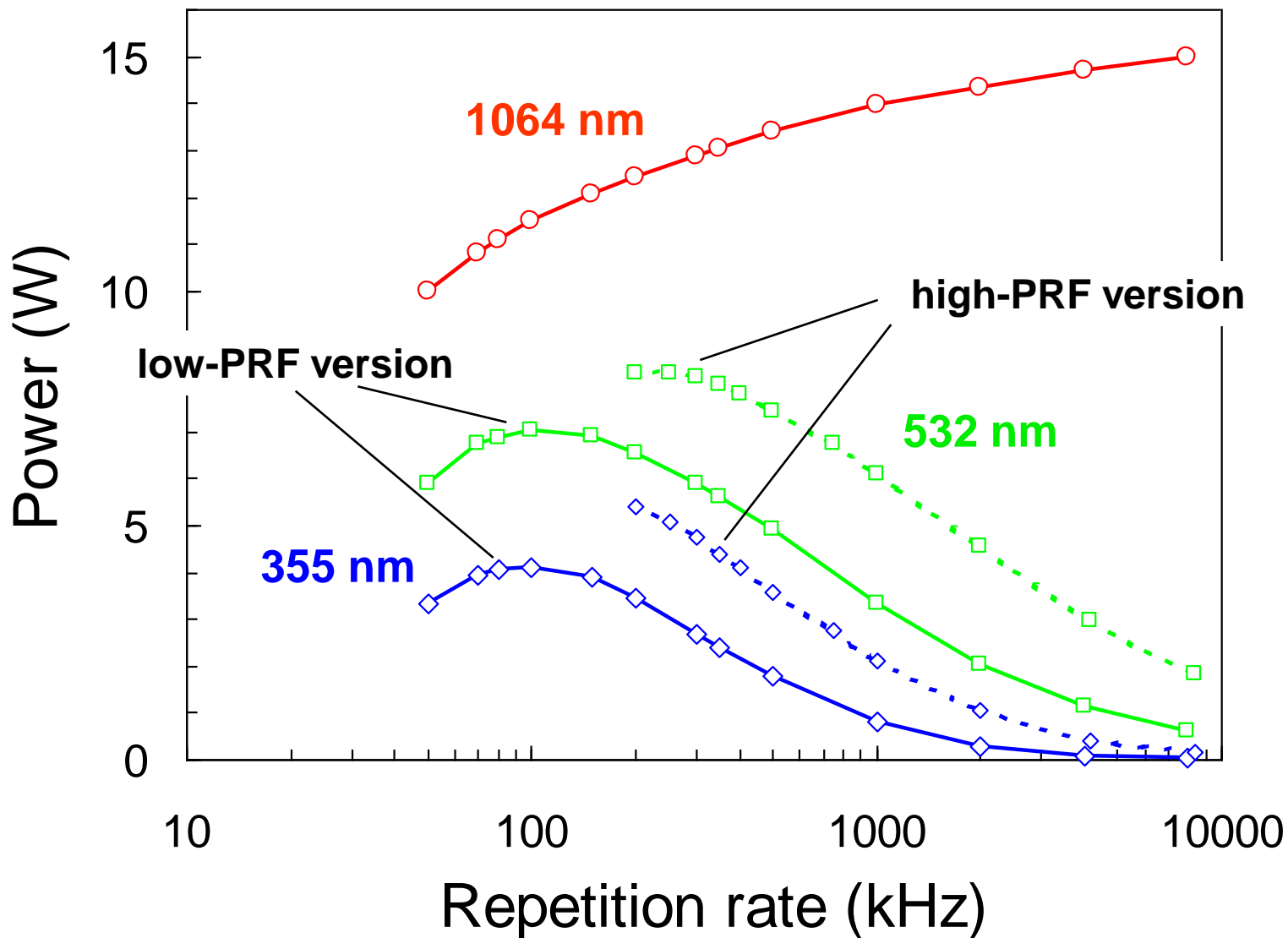
DUETTO family of modular customizable options

- FUEGO power booster to >50W average power
- Frequency Conversion
 - to 532 nm (green): >60% conversion efficiency
 - to 355 nm (UV): >35% conversion efficiency
 - to 266 nm or other wavelengths also available
 - fixed, manual, or auto (software) switching
- Pulse on demand – POD - highest speed pulse control
 - Individually triggerable pulses single-shot to 4 MHz, digital or analog gating
 - or arbitrary groups of pulses
 - prevents typical pre-pulse or first-pulse overshoot often seen in other systems
 - **FlexBurst™ technology**
- Other options
 - timing synchronization to external clock with sub-picosecond accuracy
 - variable (switchable) pulsewidths
 - repetition rate at oscillator output (80 MHz typical)



➔ **Optimized parameters for targeted process**

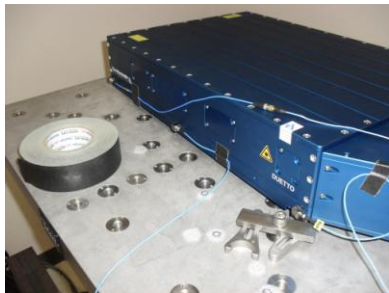
Flexibility: Wavelengths



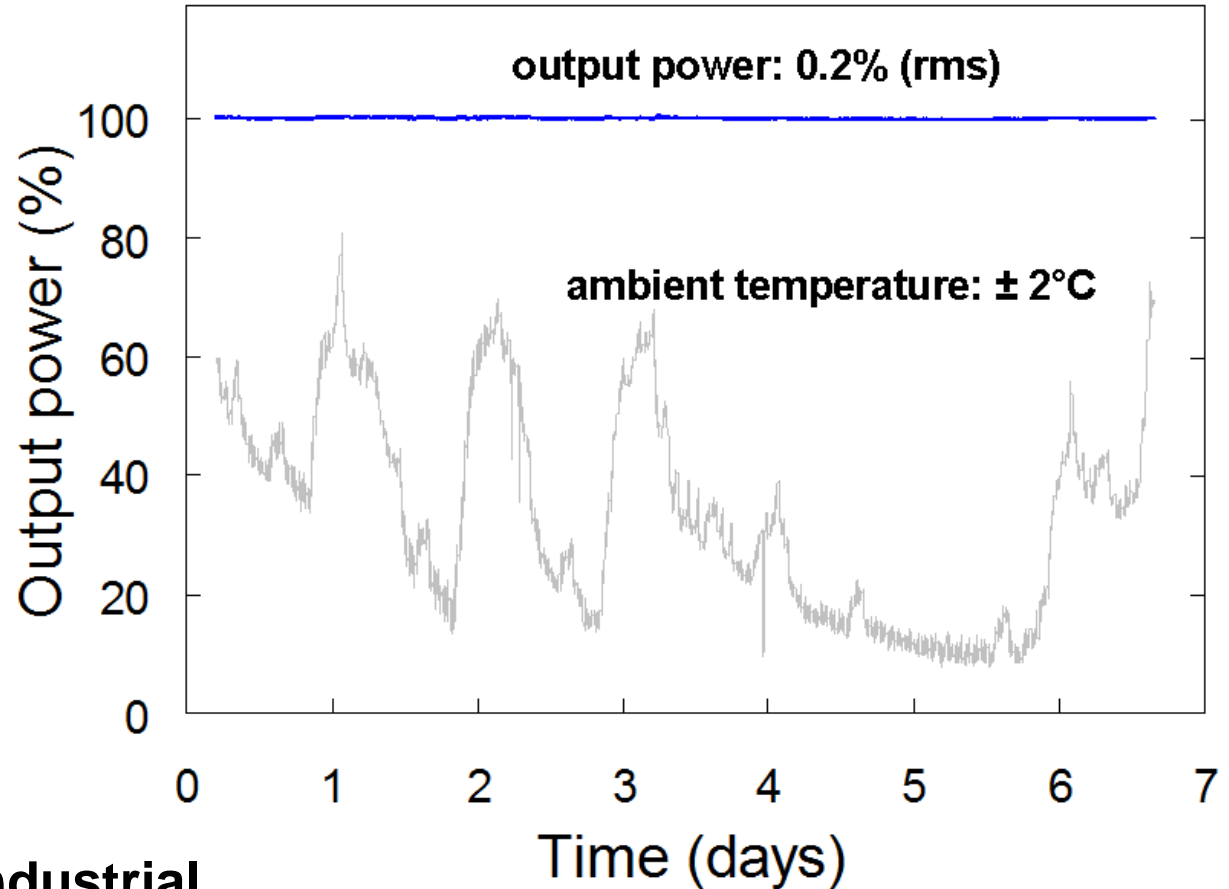
SHG > 60%

THG > 35%

DUETTO – excellent long-term stability characteristics



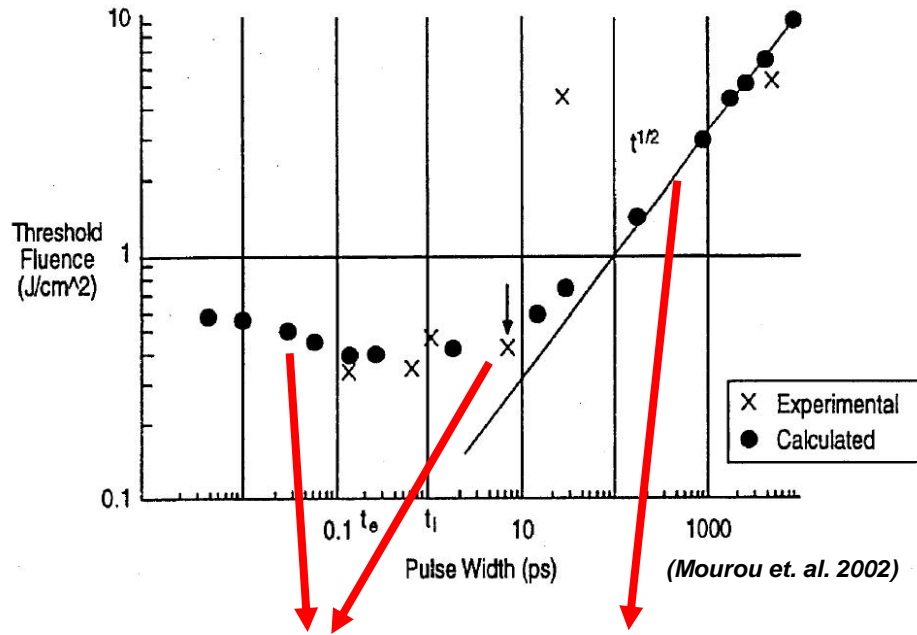
passes standardized industrial shock and vibration testing



Cold ablation – simple guidelines



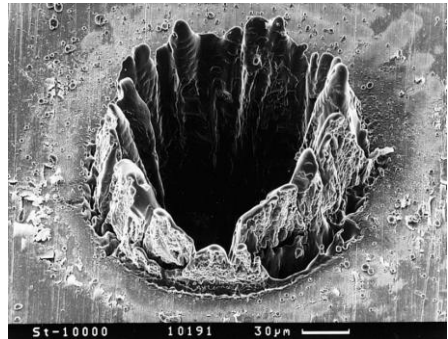
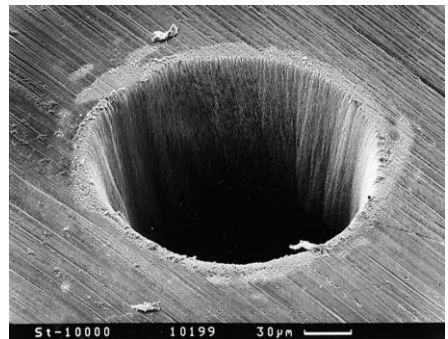
Cold ablation \Rightarrow operate near threshold fluence \Rightarrow need moderate pulse energy



$$fluence = \frac{pulse\ energy}{beam\ area}$$

High quality ablation is a **gentle** process, it requires:

- ✓ **short pulses**
typically < 10 ps
- ✓ **high enough fluence**
typically > 1 J/cm²
- &
- ✓ **not too high fluence**
typically < 2 x threshold



Chichkov, et al., *Appl. Phys. A* **63**, 109 (1996)

Typical cold ablation numbers



Example :

$$F_{\text{threshold}} = 1 \text{ J/cm}^2$$

$$F_{\text{operation}} = 1.5 \text{ J/cm}^2$$

$$\text{Area} = 500 \text{ } \mu\text{m}^2$$

(~25 μm spot diameter)

$$\left. \begin{array}{l} F_{\text{threshold}} = 1 \text{ J/cm}^2 \\ F_{\text{operation}} = 1.5 \text{ J/cm}^2 \\ \text{Area} = 500 \text{ } \mu\text{m}^2 \\ \text{(} \sim 25 \text{ } \mu\text{m spot diameter)} \end{array} \right\} E = 10 \text{ } \mu\text{J at focus}$$

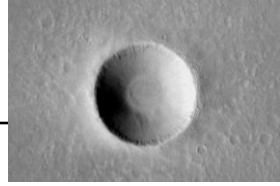
high quality processing



moderate pulse energy



“True” variable pulse rate is important



High power, fixed pulse rate laser
(e.g. 40W, 400kHz, 100 μ J) :

typical process requires 10 μ J → MUST ATTENUATE 10X

High power, variable pulse rate laser
(e.g. 40W, **200kHz – 8MHz, 200 μ J – 5 μ J**) :

typical process requires 10 μ J

→ set pulse rate to 4MHz (and use full laser power)

Variable pulse rate gives more speed



Typical ablation rate (for most materials):

$$r_A = 0.1 \text{ mm}^3/\text{min per Watt}$$

⇒ slow ⇒ speed is an important (cost) factor

$$\text{process speed} = \text{laser power} * r_A$$

determined by material & process

$$\text{laser power} = E * \text{PRF} = F * A * \text{PRF}$$

Pulse Repetition Frequency

beam area ← process feature size

pulse fluence ← just above ablation threshold

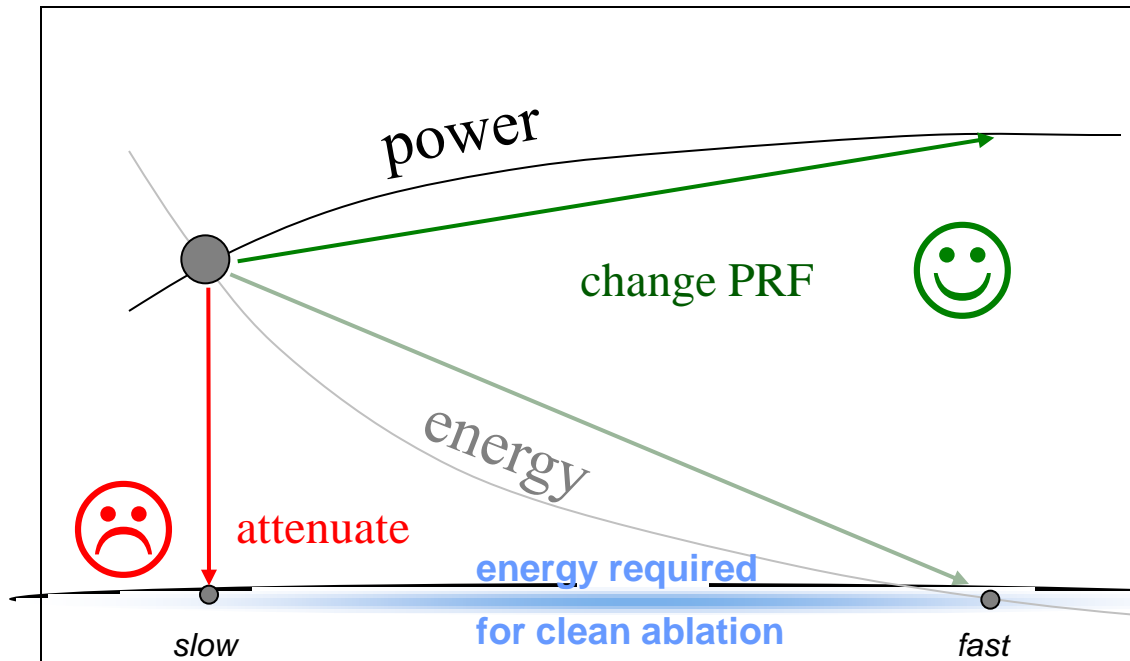
pulse energy E determined by material and process requirements

$$\text{process speed} = F * A * r_A * \text{PRF}$$

set by material and process



"True" variable pulse rate gives speed



laser # 1: fixed PRF
⇒ energy must be adjusted via attenuation

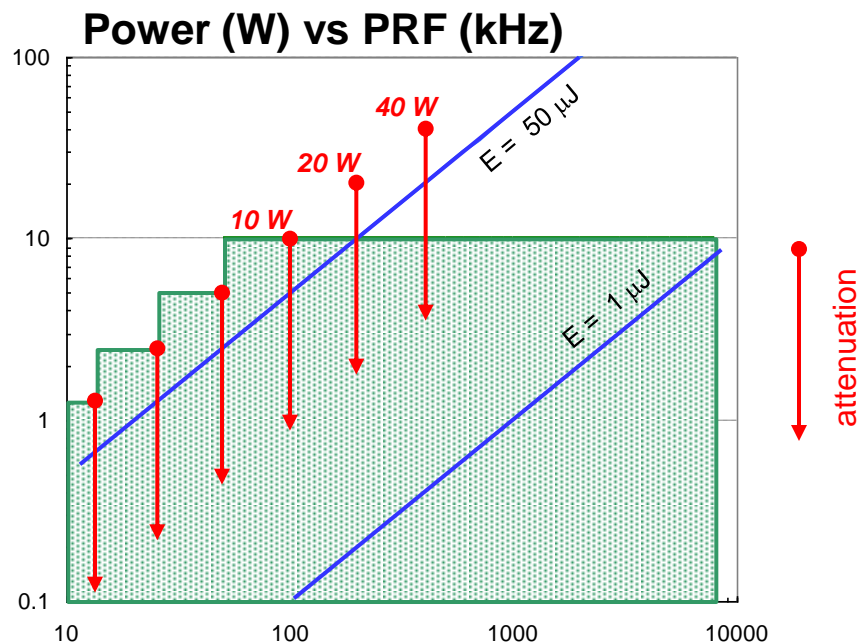
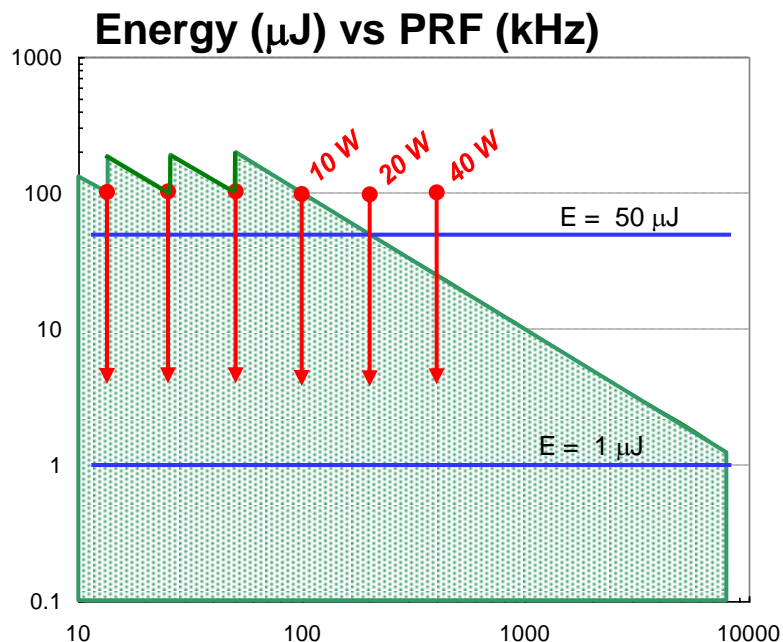
laser # 2: variable PRF
⇒ energy can be adjusted via PRF

PRF [= process speed]

variable PRF ⇔ higher process speed



Variable PRF - better process optimization



blue curves: areas between $E=1 \mu\text{J}$ and $E=50 \mu\text{J}$ denote parameter space for typical applications

laser # 1: fixed PRF (40W @ 400kHz), equipped with “pulse on demand” system

⇒ covers red arrows in parameter space

laser # 2: variable PRF (10W @ 50kHz-8MHz), equipped with “pulse on demand” system

⇒ covers green area in parameter space

Although laser # 1 is more powerful (40W), laser #2 (10W) covers a much broader area in the application parameter space due to the flexibility of its PRF. This is a clear advantage because the parameter window for many applications is small and thus requires fine adjustments of the pulse energy as well as the PRF.



Flexibility: Pulse on Demand option

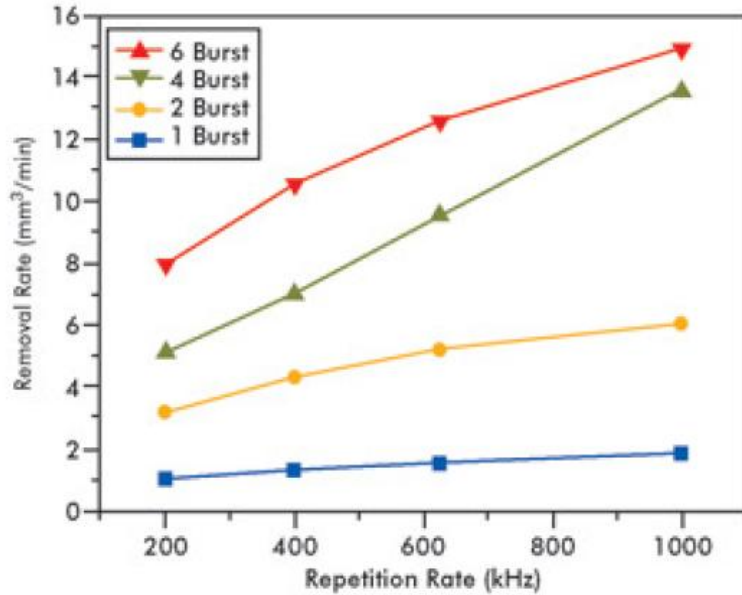


Pulse on Demand (PoD) – full user control over DUETTO pulse timing

- Fast digital switching (pulse / no pulse) with single-pulse precision up to > 4 MHz with **no first-pulse problem**
 - via TTL user input or software-controlled
- Fast analog modulation (e.g. attenuation)
 - via analog user input or software-controlled



Flexibility: Why burst mode?

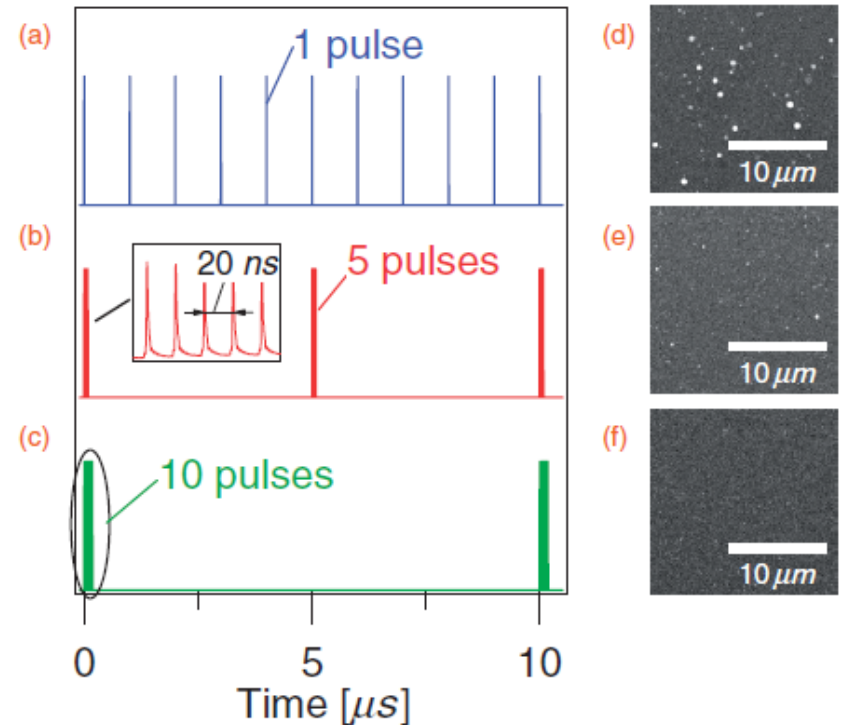


Burst mode increases ablation rate

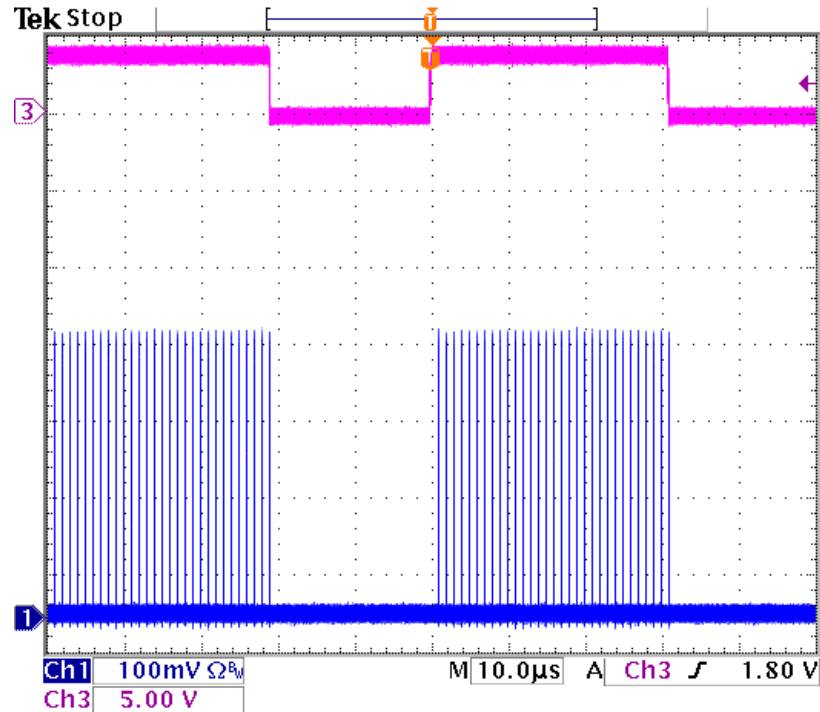
Phot. Spectra, issue 11, 2009.
(Ablation of Si)

Burst mode improves deposition rate and surface smoothness

Applied Physics Express 2 (2009) 042501
(Deposition of TiO₂ thin film)



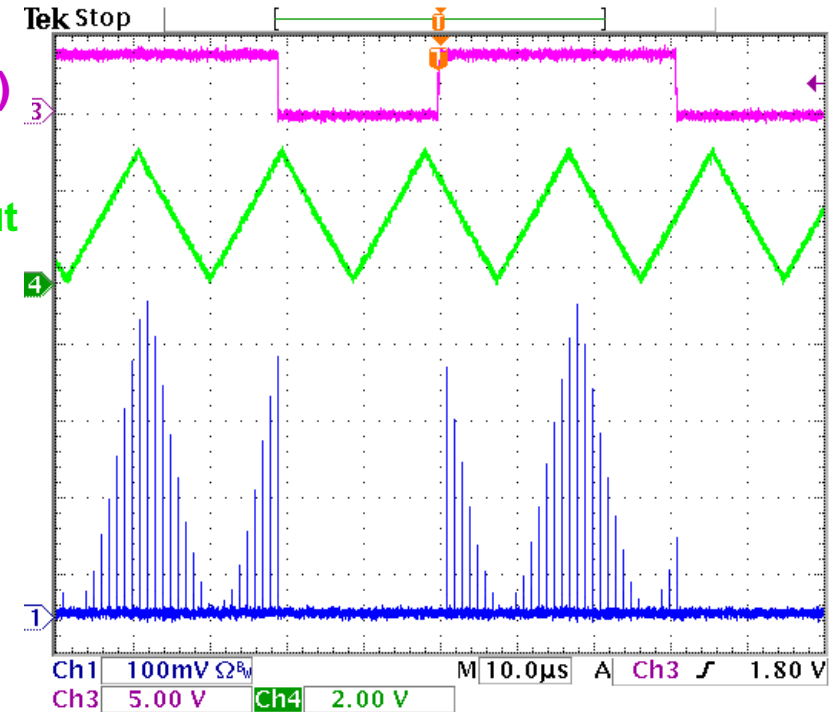
Flexibility: PoD digital & analog modulation



Digital input (TTL)

Analog user input

Optical output



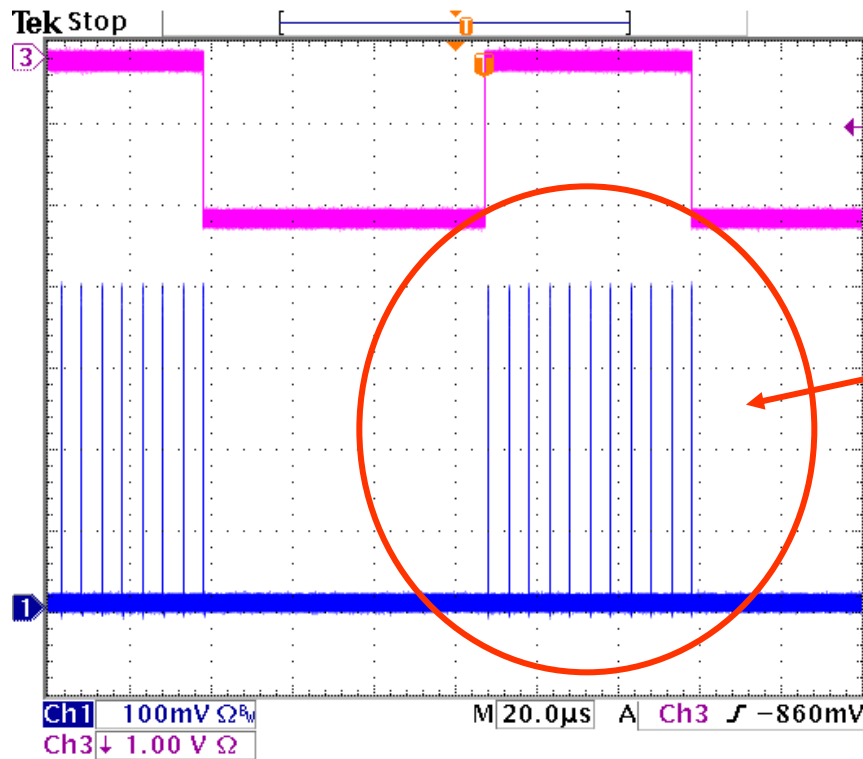
⇒ Fast and simple analog modulation
(e.g., attenuation of laser output)

Flexibility: FlexBurst™ feature



First, some terminology:

Burst: a group of pulses with a spacing in the order of 10 nanoseconds.
The burst is repeated with the PRF.



We do NOT call this burst...
Spacing of pulses is
5 microsec (= 1/200 kHz)

Flexibility: FlexBurst™ feature

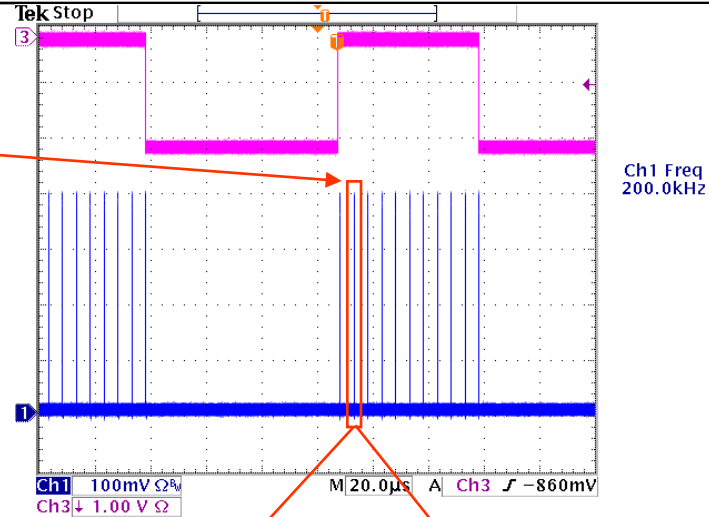


... but each of these “lines”
can consist of a burst

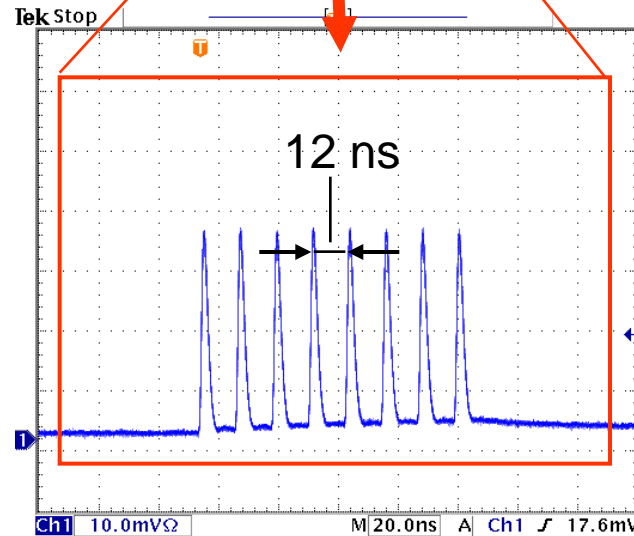
A regenerative amplifier
can offer you this...
(with single pulses)

...but not this!

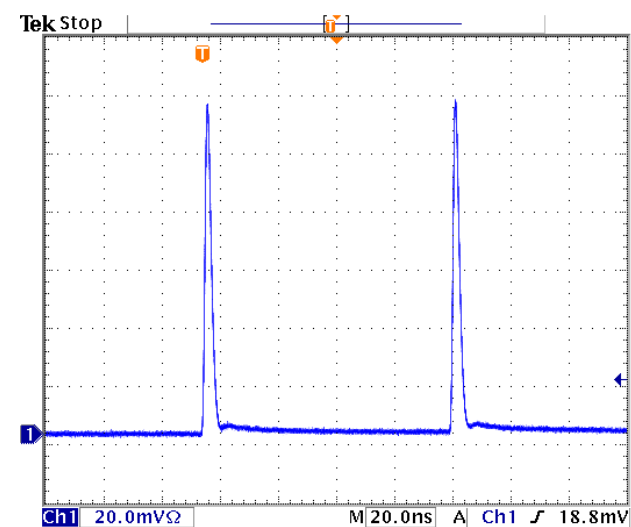
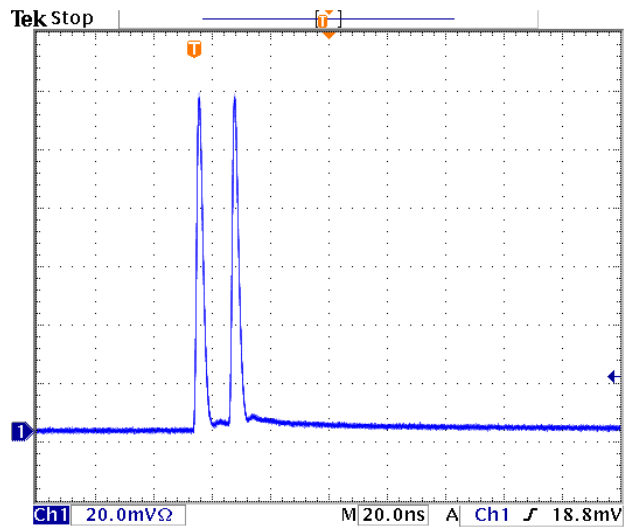
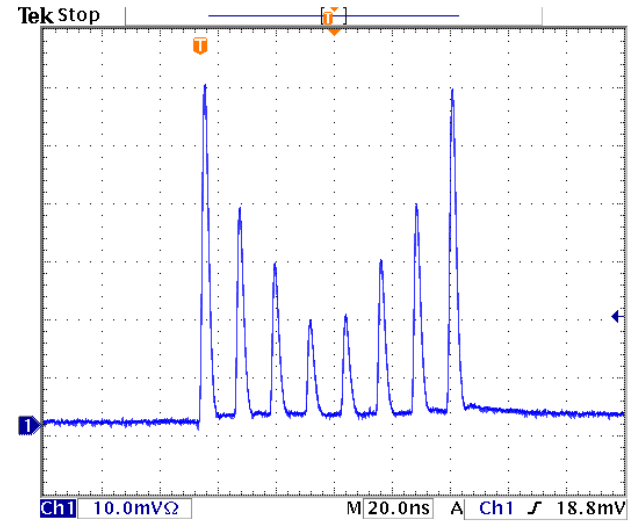
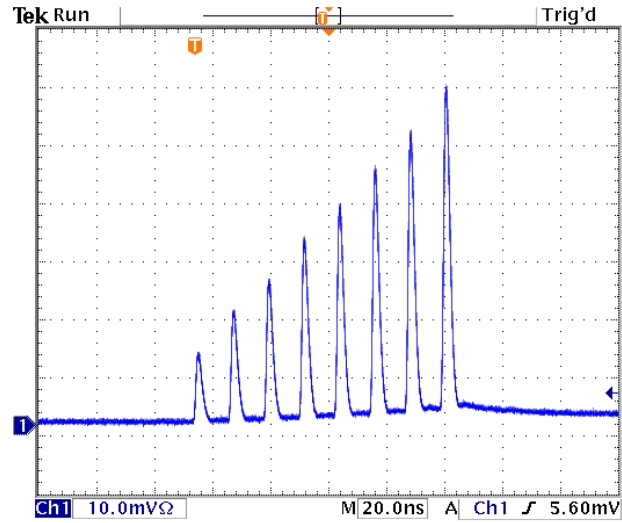
FlexBurst™!



Zoom 1000x



Flexibility: FlexBurst™ – a few examples

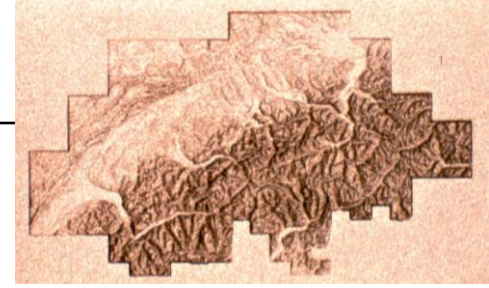


Summary

- **Picosecond lasers offer improved quality, faster processing speed for “fine” ablation processes**
- **Duetto – flexible, modular industrial picosecond system for micromachining**
 - **Broad repetition rate range for effective process optimization**
 - **Wavelength flexibility (IR, green, UV)**
 - **High-power add-on module**
 - **FlexBurst pulse control**
- **Thin-film, surface, microstructuring applications**
 - **Precision machinery, semiconductor, biotech, solar cell, security,**

Thanks for your attention!

DUETTO™ product family offers



- Modular options
- Flexibility
- Industrial Reliability
- Optimized process
- Cost-efficiency

